

L Number	Hits	Search Text	DB	Time stamp
1	3	5376902.URPN.	USPAT	2004/10/28 09:01
2	8	("4350958"   "4386324"   "4626889"   "4831497"   "5027088"   "5039824"   "5223741"   "5223804").PN.	USPAT	2004/10/28 09:15
3	43	4831497.URPN.	USPAT	2004/10/28 09:17
4	8	("2550409"   "2984802"   "3543198"   "3876822"   "4157612"   "4495479"   "4498122"   "4571451").PN.	USPAT	2004/10/28 09:25
-	7	US-5499445-\$.DID. OR US-6376906-\$.DID. OR US-6355978-\$.DID. OR US-6369443-\$.DID. OR US-6373717-\$.DID. OR US-6362525-\$.DID. OR US-5779503-\$.DID.	USPAT; US-PGPUB; EPO; JPO	2004/10/27 17:50
-	23906	(cross adj talk) "cross-talk"	USPAT; US-PGPUB; EPO; JPO	2004/10/27 18:00
-	61898	semiconductor and (chip die) and (package packaging)	USPAT; US-PGPUB; EPO; JPO	2004/10/27 17:52
-	1853892	substrate carrier	USPAT; US-PGPUB; EPO; JPO	2004/10/27 17:53
-	1411	((cross adj talk) "cross-talk") and (semiconductor and (chip die) and (package packaging)) and (substrate carrier)	USPAT; US-PGPUB; EPO; JPO	2004/10/27 17:55
-	8296	((cross adj talk) "cross-talk") with (reduc\$3 minimized minimize)	USPAT; US-PGPUB; EPO; JPO	2004/10/27 18:00
-	602	((cross adj talk) "cross-talk") with (reduc\$3 minimized minimize) and (semiconductor and (chip die) and (package packaging)) and (substrate carrier)	USPAT; US-PGPUB; EPO; JPO	2004/10/27 18:01
-	481	((cross adj talk) "cross-talk") with (reduc\$3 minimized minimize) and (semiconductor and (chip die) and (package packaging)) and (substrate carrier)) and (pad (conductive adj via) conductor)	USPAT; US-PGPUB; EPO; JPO	2004/10/27 18:01
-	469	((cross adj talk) "cross-talk") with (reduc\$3 minimized minimize) and (semiconductor and (chip die) and (package packaging)) and (substrate carrier)) and (pad (conductive adj via) conductor)) and (method process)	USPAT; US-PGPUB; EPO; JPO	2004/10/27 17:57
-	224	((cross adj talk) "cross-talk") with (reduc\$3 minimized minimize) and (semiconductor and (chip die) and (package packaging)) and (substrate carrier)) and (pad (conductive adj via) conductor)) and (method process)) and pair	USPAT; US-PGPUB; EPO; JPO	2004/10/27 17:57
-	7	((cross adj talk) "cross-talk") with (reduc\$3 minimized minimize) and (semiconductor and (chip die) and (package packaging)) and (substrate carrier)) and (pad (conductive adj via) conductor)) and (method process)) and (second adj pair)	USPAT; US-PGPUB; EPO; JPO	2004/10/27 18:02
-	50466	(cross adj talk) "cross-talk" crosstalk	USPAT; US-PGPUB; EPO; JPO	2004/10/27 18:00
-	17373	((cross adj talk) "cross-talk" crosstalk) with (reduc\$3 minimized minimize)	USPAT; US-PGPUB; EPO; JPO	2004/10/27 18:00

-	1186	((cross adj talk) "cross-talk" crosstalk) with (reduc\$3 minimized minimize)) and (semiconductor and (chip die) and (package packaging)) and (substrate carrier)	USPAT; US-PGPUB; EPO; JPO	2004/10/27 18:01
-	934	((cross adj talk) "cross-talk" crosstalk) with (reduc\$3 minimized minimize)) and (semiconductor and (chip die) and (package packaging)) and (substrate carrier)) and (pad (conductive adj via) conductor)	USPAT; US-PGPUB; EPO; JPO	2004/10/27 18:01
-	78	((cross adj talk) "cross-talk" crosstalk) with (reduc\$3 minimized minimize)) and (semiconductor and (chip die) and (package packaging)) and (substrate carrier)) and (pad (conductive adj via) conductor)) and (second adj pair)	USPAT; US-PGPUB; EPO; JPO	2004/10/27 18:02